

S/N 09/901001

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. Ahn et al. Examiner: Kathleen Duda  
Serial No.: 09/901001 Group Art Unit: 1756  
Filed: July 09, 2001 Docket: 1303.016US1  
Title: COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI METALIZATION

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**INFORMATION DISCLOSURE STATEMENT**

MS RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. § 1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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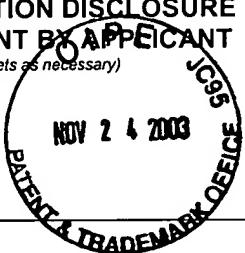
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21st day of November, 2003.

Name

Amy Moriarty

Signature

Amy Moriarty

Substitute for form 1449A/PTO <b>INFORMATION DISCLOSURE      STATEMENT BY APPLICANT</b> <small>(Use as many sheets as necessary)</small>		Complete if Known	
		Application Number	09/901001
		Filing Date	July 9, 2001
		First Named Inventor	Ahn, Kie
		Group Art Unit	1756
		Examiner Name	Duda, Kathleen
Sheet 1 of 1		Attorney Docket No: 1303.016US1	

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### US PATENT DOCUMENTS

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	US-5,814,557	09/29/1998	Venkatraman, Ramnath , et al.	438	622	05/20/1996
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### FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T <sup>2</sup>

### OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
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		"SiLK* J SEMICONDUCTOR DIELECTRIC RESIN", <u>The DOW Company, www.silk.dow.com, (unknown)</u> ,2	
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		MARTIN, STEVEN J., "THE INVENTION AND DEVELOPMENT OF A LOW-DIELECTRIC CONSTANT POLYMER FOR THE FABRICATION OF INTEGRATED CIRCUIT INTERCONNECT", <u>Seminar Department of Chemical Engineering, North Carolina State University, (April 9, 2001)</u> ,1	
		ZHANG, F , et al., "Nanoglass TM E Copper Damascene Processing for Etch, Clean, and CMP", <u>www.electronicmaterials.com/star_center/technical_papers.html, (2001)</u> ,6	

EXAMINER

DATE CONSIDERED